



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251124000.2

**Qualify UTL as an additional Assembly/Test site for select devices
Change Notification / Sample Request**

Date: November 24, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251124000.2
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CAXC4T774QRSVRQ1	NULL
CAXC4T245QRSVRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251124000.2		PCN Date:	November 24, 2025													
Title:	Qualify UTL as an additional Assembly/Test site for select devices																
Customer Contact:	Change Management team		Dept:	Quality Services													
Proposed 1st Ship Date:	May 23, 2026		Sample requests accepted until:	January 23, 2026*													
*Sample requests received after January 23, 2026 will not be supported.																	
Change Type:																	
☒	Assembly Site	☐	Design	☐	Wafer Bump Material												
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process												
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site												
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Material												
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process												
PCN Details																	
Description of Change:																	
Texas Instruments is pleased to announce the qualification of UTL (Subcon) as an additional Assembly/Test site for the list of devices shown below. Material differences between sites are as follows. <table border="1" style="margin: 10px auto; width: 80%;"> <thead> <tr> <th></th> <th>Current Site</th> <th>Additional Site</th> </tr> </thead> <tbody> <tr> <td>Assembly Site</td> <td>ATXSZ</td> <td>UTL</td> </tr> <tr> <td>Bond Wire Material</td> <td>Au (0.8mil)</td> <td>Au(1.0mil)</td> </tr> <tr> <td>Mount Compound</td> <td>SID#1400336111</td> <td>SID#PZ0076</td> </tr> </tbody> </table> Qual details are provided in the Qual Data Section. Test coverage, insertions, conditions will remain consistent with current testing.							Current Site	Additional Site	Assembly Site	ATXSZ	UTL	Bond Wire Material	Au (0.8mil)	Au(1.0mil)	Mount Compound	SID#1400336111	SID#PZ0076
	Current Site	Additional Site															
Assembly Site	ATXSZ	UTL															
Bond Wire Material	Au (0.8mil)	Au(1.0mil)															
Mount Compound	SID#1400336111	SID#PZ0076															
Reason for Change:																	
Continuity of supply.																	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																	
None.																	
Impact on Environmental Ratings																	
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table style="width: 100%;"> <thead> <tr> <th style="text-align: center;">RoHS</th> <th style="text-align: center;">REACH</th> <th style="text-align: center;">Green Status</th> <th style="text-align: center;">IEC 62474</th> </tr> </thead> <tbody> <tr> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> </tr> </tbody> </table>						RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change				
RoHS	REACH	Green Status	IEC 62474														
☒ No Change	☒ No Change	☒ No Change	☒ No Change														
Changes to product identification resulting from this PCN:																	

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ATXSZ	ASN	CHN	Suzhou
UTL	UTL1/3	TH	Bangkok

Sample product shipping label (not actual product label)



Product Affected:

CAXC4T245QRSVRQ1	CAXC4T774QRSVRQ1	H14T245QRSVRQ1-NT
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Automotive Qualification Summary (As per AEC-Q100 Rev. J and JEDEC Guidelines) Approve Date 12-November-2025

Product Attributes

Attributes	Qual Device: <u>CAXC4T774QRSVRQ1</u>	QBS Process Reference: <u>SN3257QDYRQ1</u>
Automotive Grade Level	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125
Product Function	Interface	Interface
Wafer Fab Supplier	RFAB	RFAB
Assembly Site	UTL3	PHI
Package Group	UXQFN	SOT
Package Designator	RSV	DYY
Pin Count	16	16

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device CAXC4T774QRSVRQ1 is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>CAXC4T774QRSVRQ1</u>	QBS Process Reference: <u>SN3257QDYRQ1</u>
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	3/Pass	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	1/45/0	-
Test Group B - Accelerated Lifetime Simulation Tests									
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	300 Hours	-	3/231/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	3/2400/0
Test Group C - Package Assembly Integrity Tests									
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>CAXC4T774QRSVRQ1</u>	QBS Process Reference: <u>SN3257QDYRQ1</u>
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	-
Test Group D - Die Fabrication Reliability Tests									
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Tddb	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests									
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1500 Volts	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-119

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and

reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-18, SEM-PA-07, SEM-PA-08

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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